

**4th DRD3 week**  
**on Solid State Detectors R&D**

**Nov 12<sup>th</sup>, 2025**



THE UNIVERSITY OF  
NEW MEXICO

# Response of AC-coupled Low Gain Avalanche Detectors to Ionizing and Non-ionizing Radiation Damage

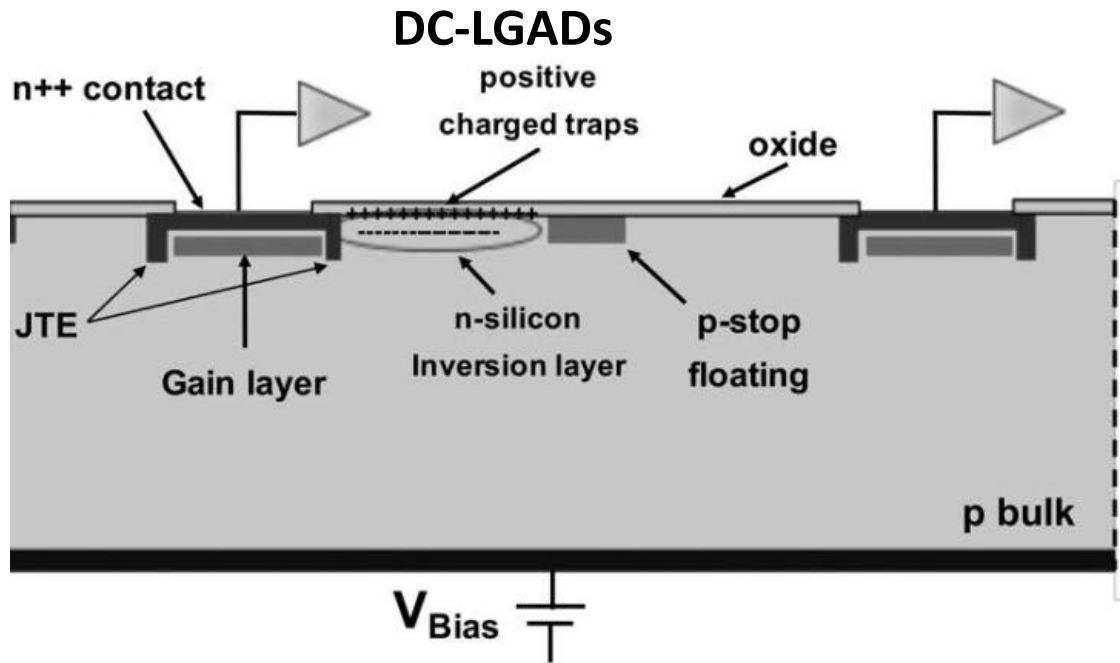
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**Brookhaven National Laboratory (BNL)**

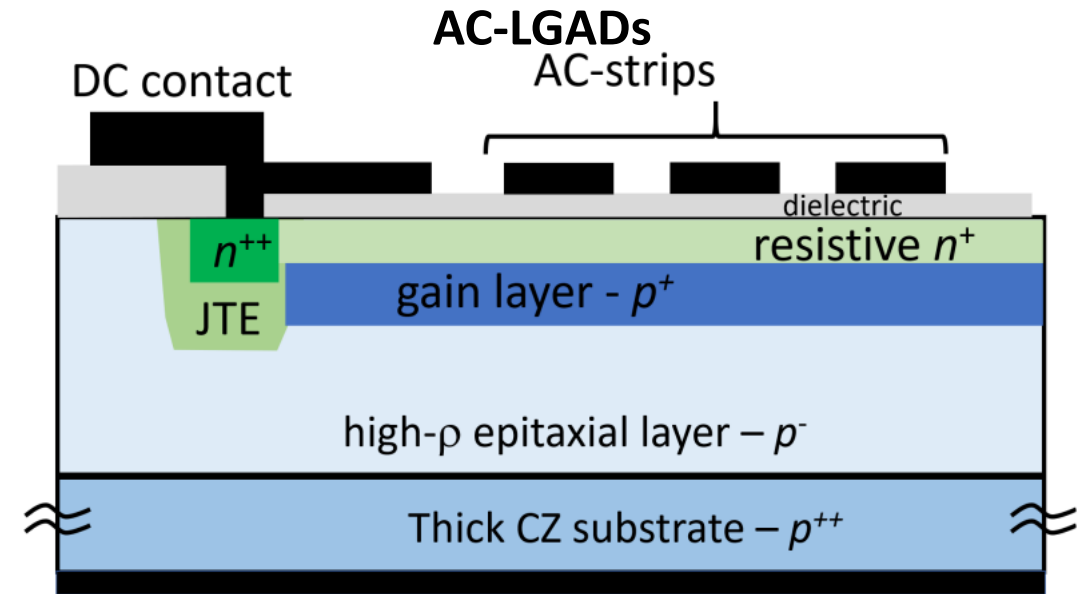
# Introduction

- Low-Gain Avalanche Detectors (LGADs) have excellent timing performance due to a doped layer that provides a moderate gain ( $\sim 10$ 's). Traditional DC LGADs' spatial resolution is limited to  $\sim 1$ mm.
- Smaller pitches can be achieved in AC-coupled LGADs (AC-LGADs) by using a continuous gain-layer and capacitively coupling the signals through a thin dielectric layer to smaller AC pads.
- Current and capacitance vs Bias (IV/CV) characterization of unirradiated/gamma-/proton-irradiated LGADs designed at Brookhaven National Lab (BNL) have been studied at the University of New Mexico (UNM).
- Acceptor Removal constants were measured.

# Difference between DC-LGAD and AC-LGAD



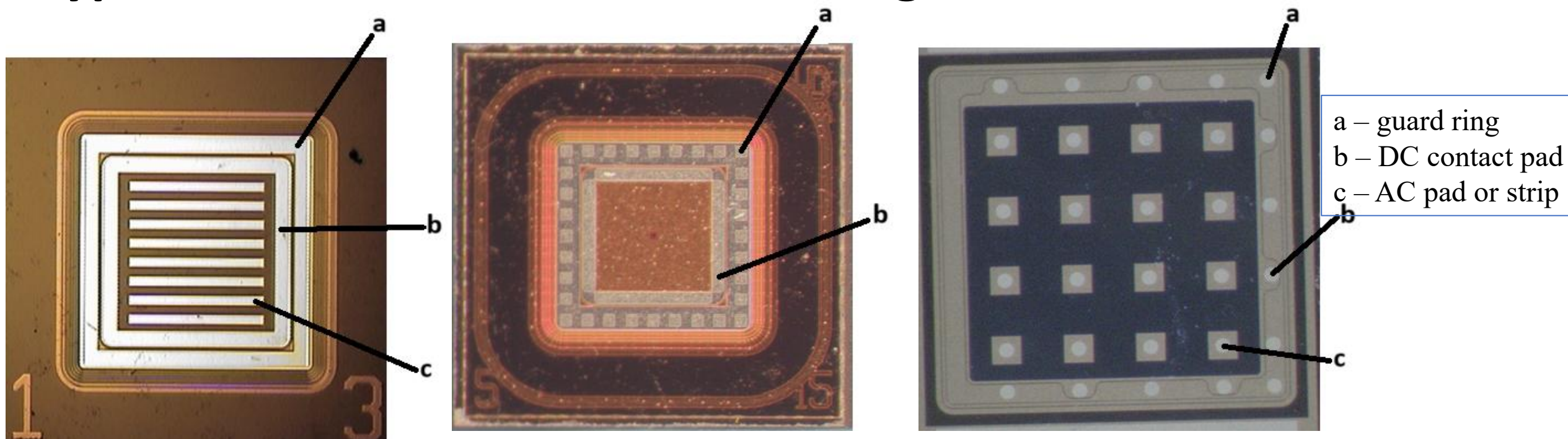
Junction Termination Extension (JTE) and p-stop/p-spray introduce no-gain region in traditional DC LGADs.



Signals can couple through the thin dielectric capacitively to AC-pads with smaller pitches.

- Thin high-resistivity epitaxial p-type substrate, ~tens of microns in thickness, atop a ~500 micron  $p^{++}$  Czochralski layer that provides ohmic contact and mechanical support.
- A doped layer that provides a moderate gain ~10's to provide large signals and make the timing resolution ~ 10's of ps.
- Traditional DC-LGAD: Due to the fill factor consideration, their spatial resolution is limited to ~ 1mm.
- AC-LGADs: by using a continuous gain-layer and coupling the signals capacitively through a thin layer of dielectric to smaller AC pads, the spatial resolution can reach ~10's of microns.

# 3 types of LGADs were irradiated by gamma and protons



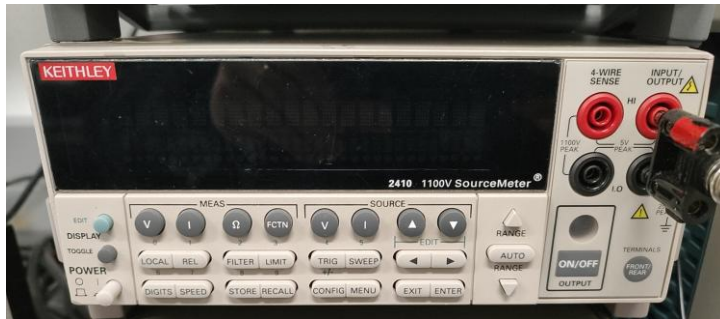
	AC-LGADs wafer 3073	DC-LGADs wafer 3076	AC-LGADs wafer 3080
Configuration	strip		pixel
Area of the n <sup>++</sup> layer (mm <sup>2</sup> )	2.05 × 2.05	1.3 × 1.3	2.05 × 2.05
Area of the gain layer (mm <sup>2</sup> )	1.95 × 1.95	1.2 × 1.2	1.95 × 1.95
Thickness of the active volume (μm)	20	20	20
Applied radiation species	gamma	proton	proton

**Gamma irradiation at Sandia National Laboratories' Gamma Irradiation Facility**

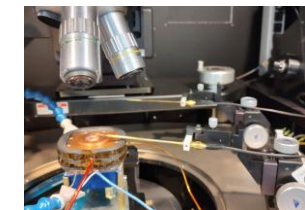
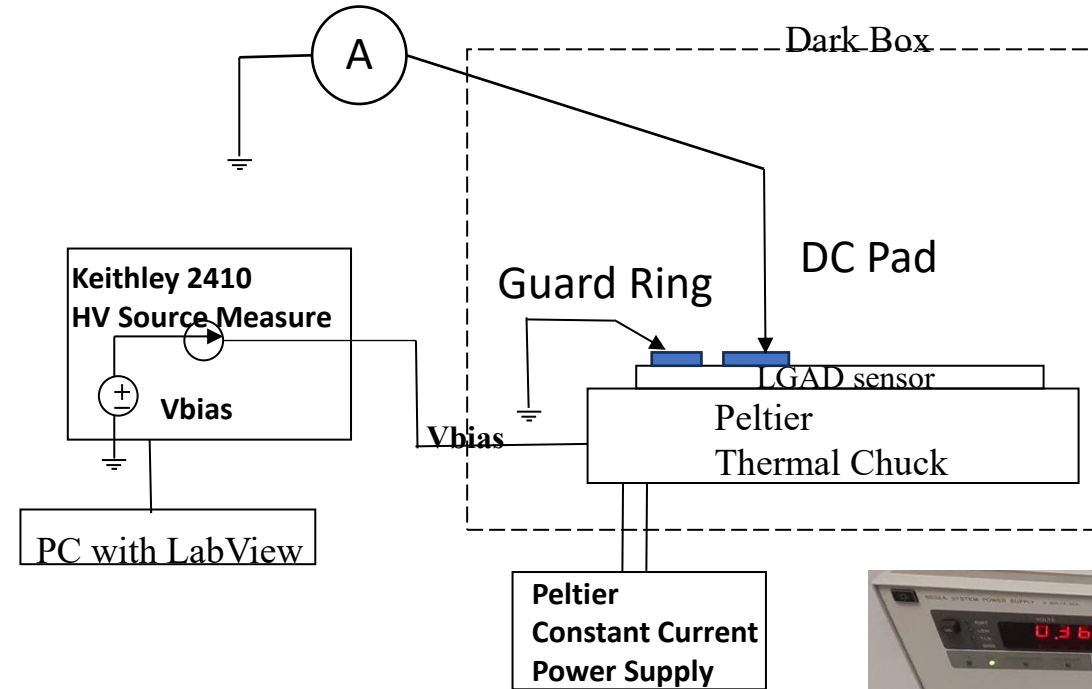
**Proton irradiation (400MeV) at Fermi National Accelerator Laboratory**



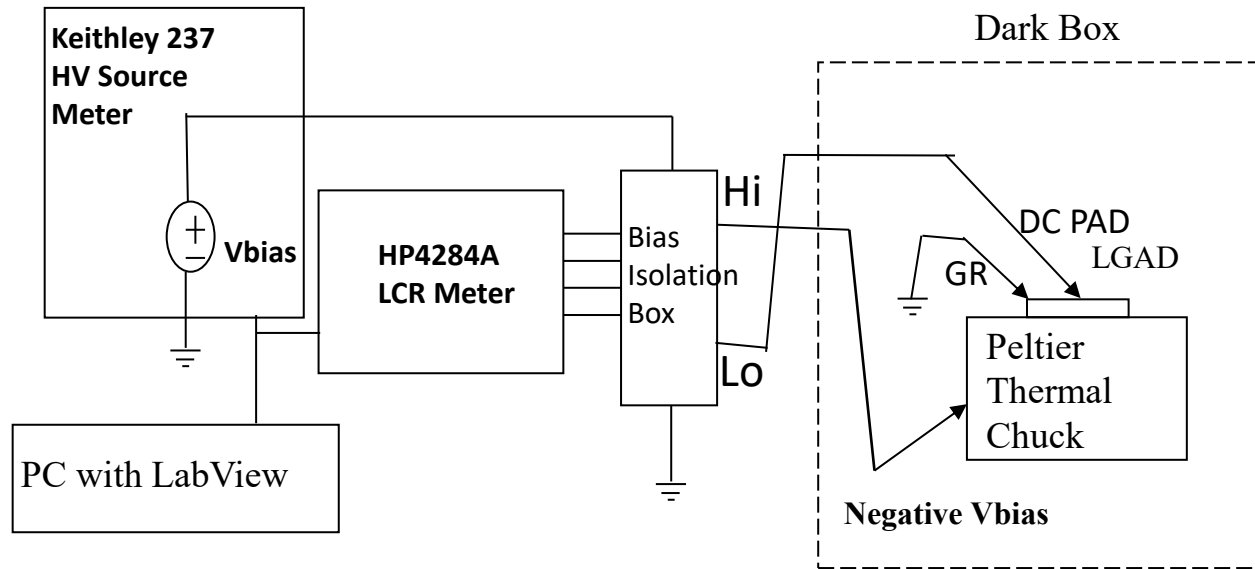
# Configuration used for Current vs. Voltage (IV) Measurement



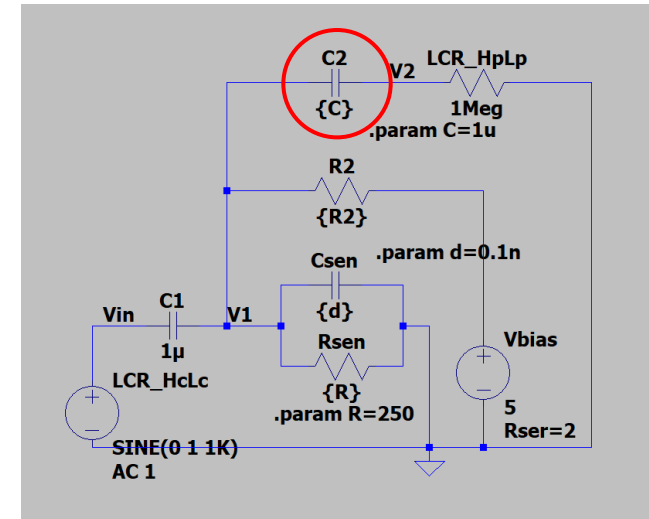
Keithley 6487 picoammeter powered through an isolation transformer



# Configuration used for CV measurement



A key capacitor in the bias isolation box has higher value (210uF) than the recommended one (1uF) by the manufacturer.



$$R_{sen} = R_{bulk}(\omega, V_{bias}) \parallel [R_{intpad}(\omega, V_{bias}) + R_{GR}(\omega, V_{bias})]$$

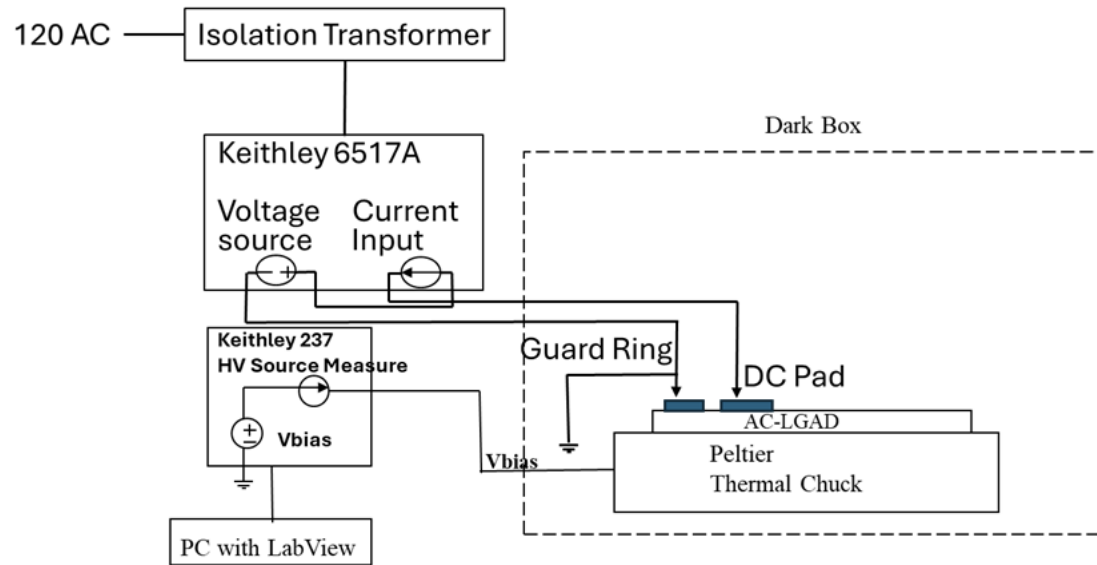
$$C_{measured} = C_{sen} - \left( \frac{1}{R_{sen}} + \frac{1}{R_2} \right) \frac{1}{C_2 R_{HpLp} \omega^2}$$

More details in backup slides

Bigger  $C_2$ ,  $\omega$  can make error smaller. However, too small  $R_{sen}$  requires an impractically big  $C_2$ .

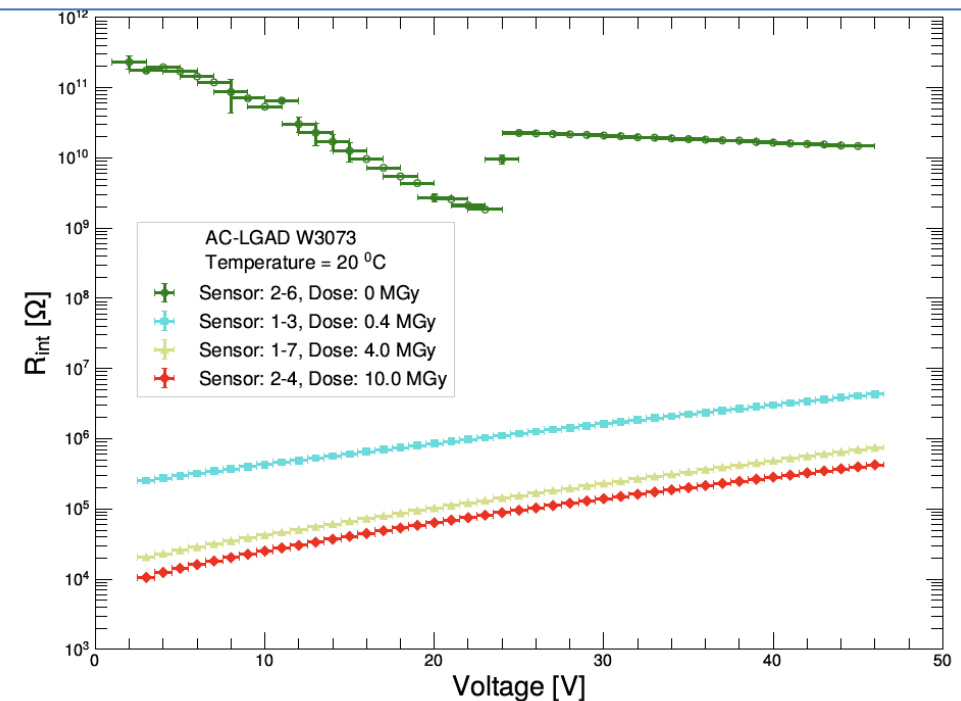
Bigger  $R_2$  can reduce error. However,  $R_2$  can't be too big because it would take too much time to make  $V_{bias}$  stable.

# Inter-pad resistance of BNL LGADs between the DC contact and the guard ring was measured to assess the effects of gamma-induced surface damage.



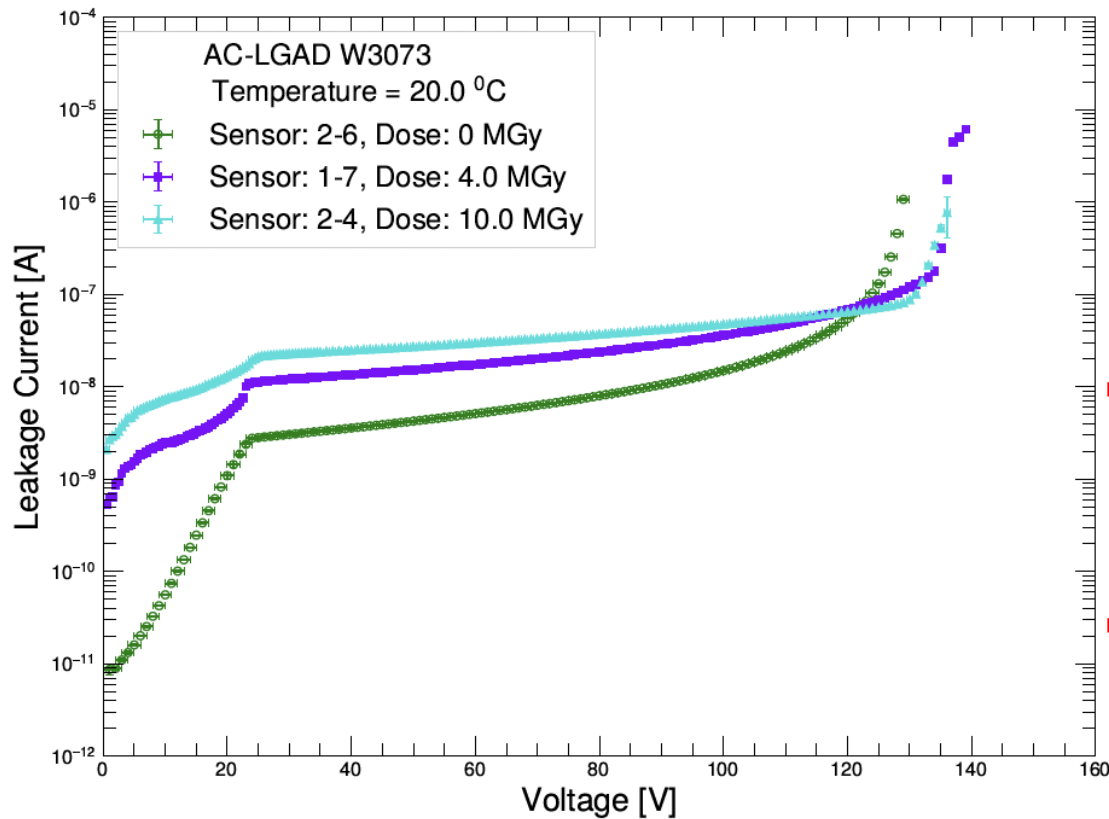
- A dip in  $R_{int}$  occurs in the unirradiated sensor at the onset of full depletion.
- Inter-pad resistance drops with increasing dose from  $10^{10} \Omega$  to below  $10^6 \Omega$ , stabilizing around dose 4 MGy.

Irradiation with gammas has been shown to increase surface oxide charge density up to saturation at doses in the range 0.1 – 1 MGy. Resistance is then dominated by the oxide charge after that point. Decreasing resistivity for doses  $> 1$  MGy is due to bulk damage in the form of point defects due to Compton electrons.



# Leakage current and breakdown voltage increase after gamma irradiation

## Gamma irradiation studies of strip AC-LGAD



- Leakage currents collected at various temperatures  $T$  in the range 19.8 – 20.0 °C are scaled to values at  $T_{ref}$  according to

$$I_{leakage}(T_{ref}) = I_{leakage}(T) \cdot \left(\frac{T_{ref}}{T}\right)^2 \cdot e^{-\frac{E_{eff}}{k_B} \left(\frac{1}{T_{ref}} - \frac{1}{T}\right)}$$

- $E_{eff} = 1.21 \text{ eV}$

- Observations: Following irradiation to 10 MGy,

- $V_{breakdown}$  increases from 120 V to 130 V

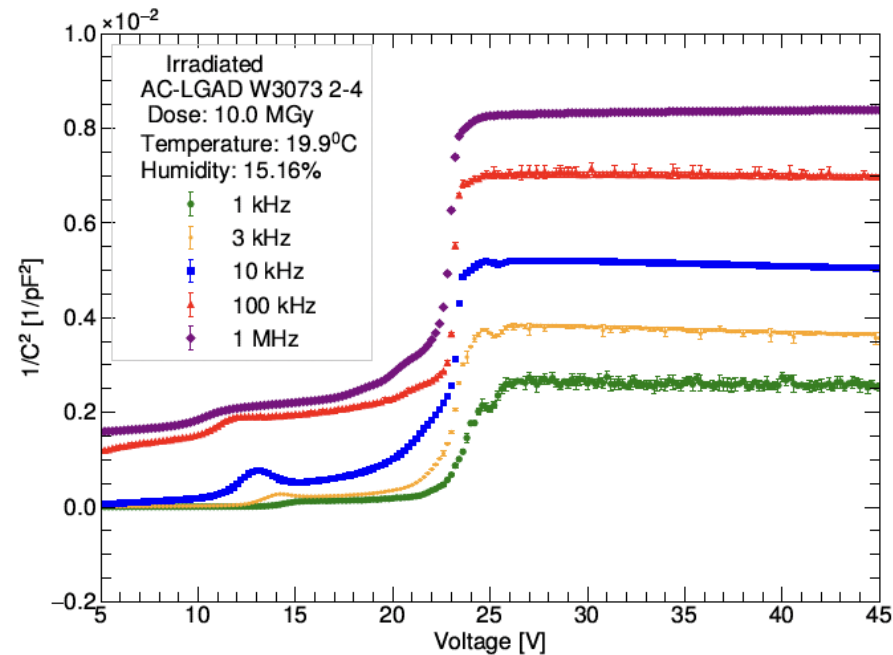
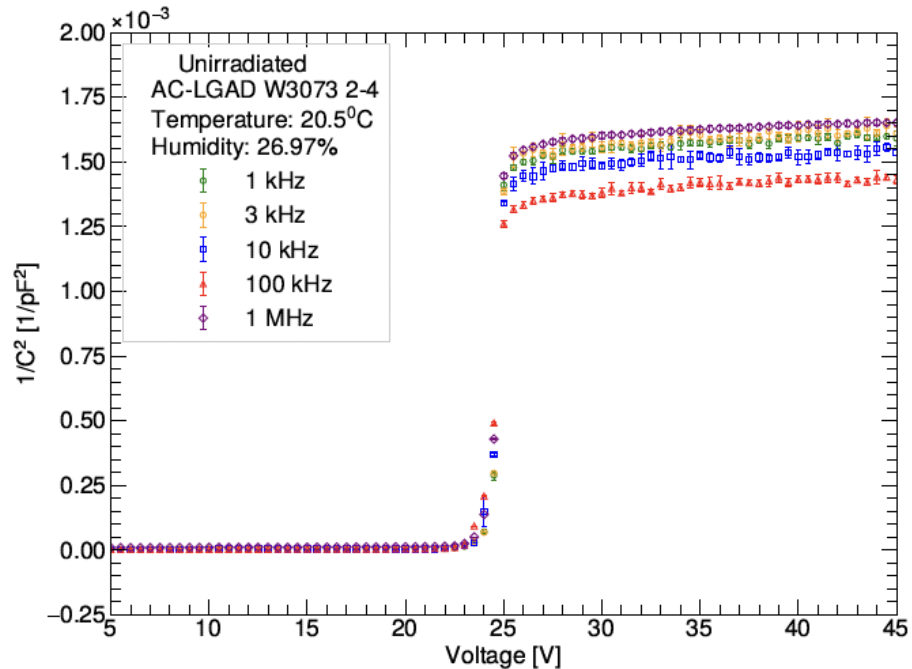
- $I_{leakage}$  increases by factor 6.3 to ~6 nA.

- $R = I_{leakage}^{irradiated} / I_{leakage}^{unirradiated}$

Dose [MGy]	Sensor number	$I_{leakage}$ [nA]	$\mathcal{R}$
0	2-6	4.4	-
0.4	1-3	-	-
4.0	1-7	15.3	$3.5 \pm 0.1$
10.0	2-4	27.3	$6.2 \pm 0.2$

Values measured at 50V

# The gain layer depletion voltage decreases up to ~2V as gamma irradiation increases

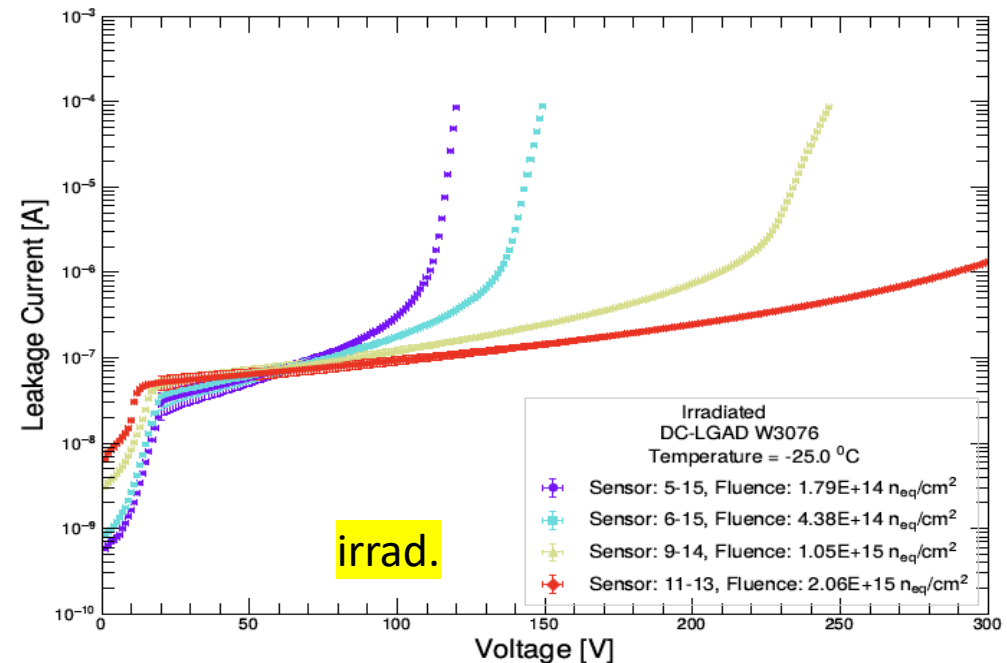
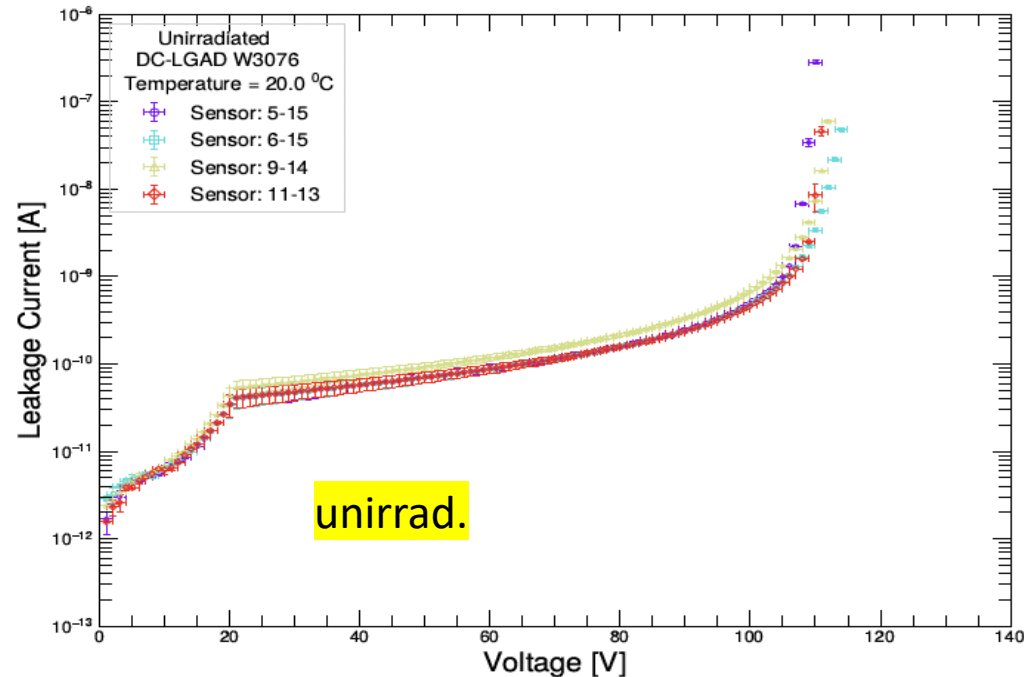


Gamma irradiation introduces frequency dependence in capacitance

Sensor	Unirradiated			Dose [MGy]	Irradiated		
	$V_{gl}$ [V]	$V_{fd}$ [V]	$V_{bulk}$ [V]		$V_{gl}$ [V]	$V_{fd}$ [V]	$V_{bulk}$ [V]
2-6	$23.3 \pm 0.6$	$25.2 \pm 0.6$	$1.9 \pm 0.9$	0.0	–	–	–
1-3	$23.3 \pm 0.6$	$25.1 \pm 0.6$	$1.8 \pm 0.8$	0.4	$23.2 \pm 0.5$	$24.8 \pm 0.6$	$1.6 \pm 0.8$
1-7	$23.2 \pm 0.6$	$25.1 \pm 0.6$	$1.9 \pm 0.8$	4.0	$22.3 \pm 0.5$	$23.8 \pm 0.6$	$1.5 \pm 0.8$
2-4	$23.7 \pm 0.6$	$25.7 \pm 0.6$	$2.0 \pm 0.9$	10.0	$21.5 \pm 0.7$	$24.2 \pm 0.4$	$2.7 \pm 0.9$

Values reported @ 10 kHz.

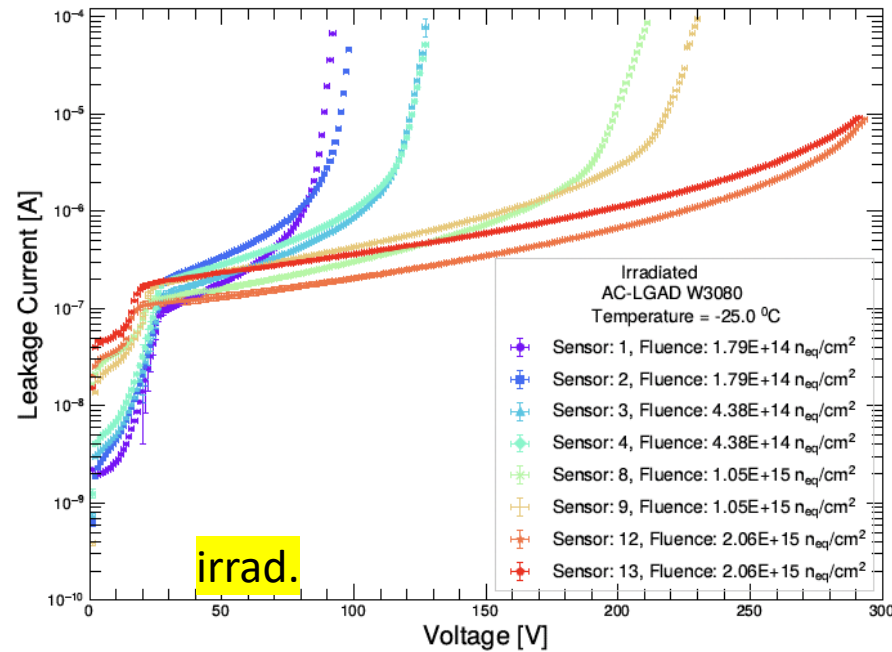
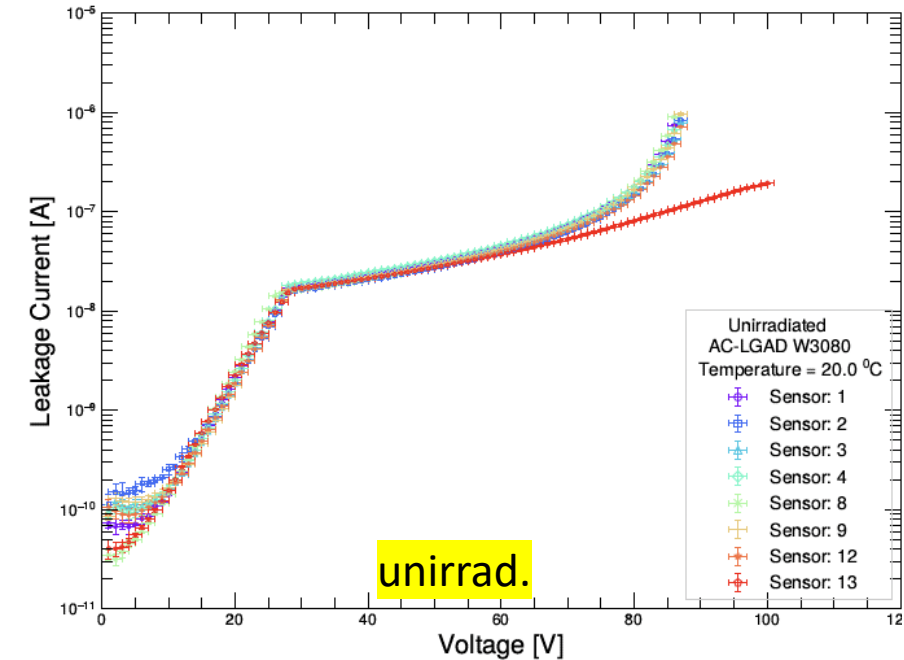
For DC-LGADs, breakdown voltage increases with proton dose; leakage current increases to  $\sim 7 \mu\text{A}$  after proton irradiation.



Fluence [400-MeV p/cm <sup>2</sup> ]	Fluence [n <sub>eq</sub> /cm <sup>2</sup> ]	Sensor number	$I_{\text{unirradiated}}$ [nA]	$I_{\text{irradiated}}$ [ $\mu\text{A}$ ]
$2 \times 10^{14}$	$1.79 \times 10^{14}$	5-15	0.07	6.0
$5 \times 10^{14}$	$4.38 \times 10^{14}$	6-15	0.07	6.6
$13 \times 10^{14}$	$1.05 \times 10^{15}$	9-14	0.09	7.4
$25 \times 10^{14}$	$2.06 \times 10^{15}$	11-13	0.07	6.9

Values measured at 50V

# For AC-LGAD, breakdown voltage increases with proton dose; leakage current increases to $\sim 22 \mu\text{A}$ .



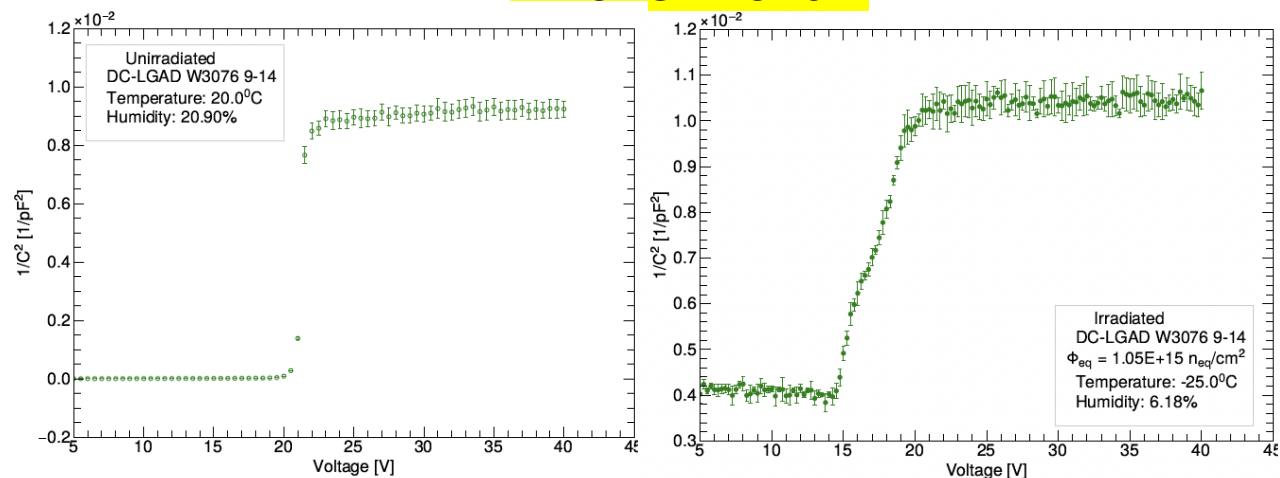
Fluence [400-MeV p/cm <sup>2</sup> ]	Fluence [n <sub>eq</sub> /cm <sup>2</sup> ]	Sensor number	$I_{\text{unirradiated}}$ [nA]	$I_{\text{irradiated}}$ [μA]
$2 \times 10^{14}$	$1.79 \times 10^{14}$	1	31	19
		2	27	26
$5 \times 10^{14}$	$4.38 \times 10^{14}$	3	29	23
		4	33	30
$13 \times 10^{14}$	$1.05 \times 10^{15}$	8	28	17
		9	30	25
$25 \times 10^{14}$	$2.06 \times 10^{15}$	12	28	14
		13	28	25

Values measured at 50V

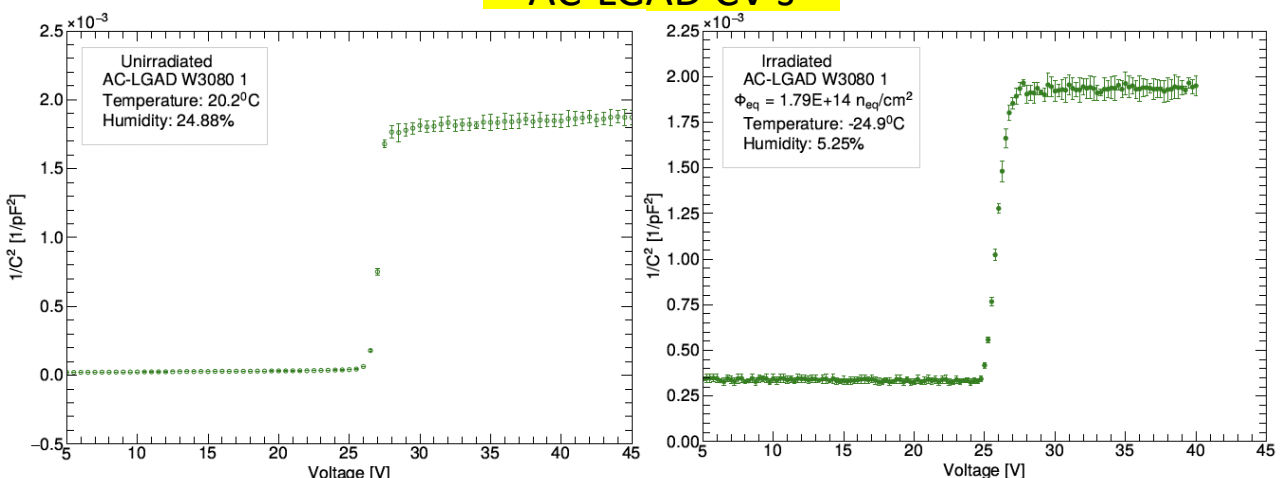
Given that the area of AC-LGADs is  $\sim \times 2.5$  of that of DC-LGADs, the change of leakage current after irradiation is qualitatively consistent between DC- and AC-LGADs.

# The gain layer depletion voltage decreases (up to ~ 10V) as proton irradiation increases

---DC-LGAD CV's---



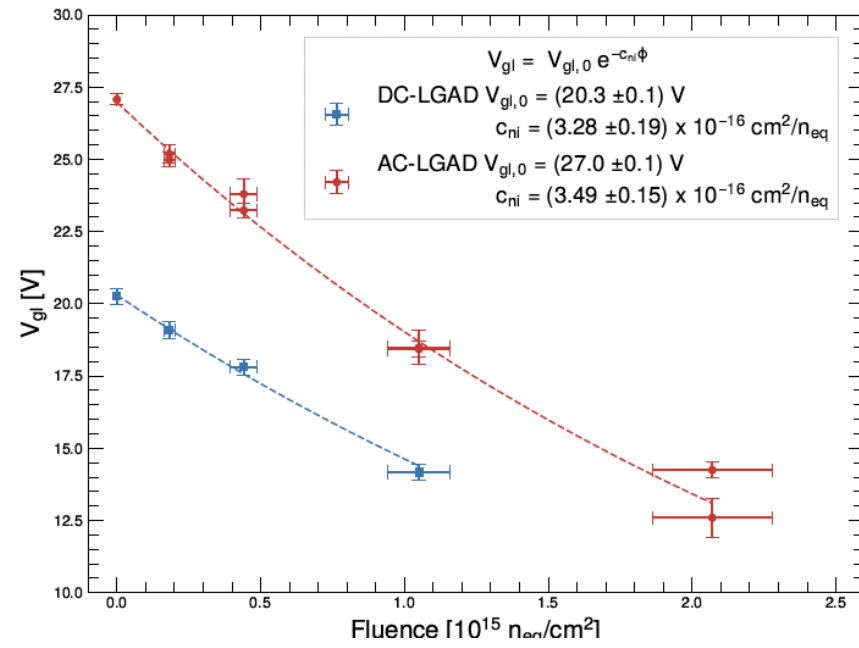
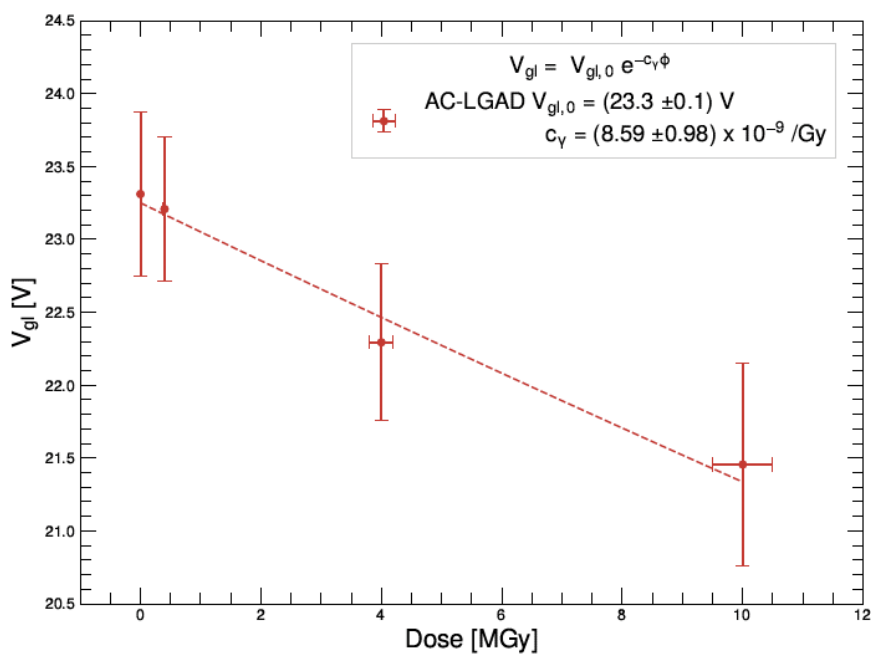
---AC-LGAD CV's---



Sensor	Unirradiated			Fluence [neq/cm <sup>2</sup> ]	Irradiated		
	V <sub>gl</sub> [V]	V <sub>fd</sub> [V]	V <sub>bulk</sub> [V]		V <sub>gl</sub> [V]	V <sub>fd</sub> [V]	V <sub>bulk</sub> [V]
5-15	20.3 ± 0.6	22.1 ± 0.6	1.8 ± 0.8	1.79E+14	19.1 ± 0.3	21.0 ± 0.3	1.9 ± 0.4
6-15	20.3 ± 0.6	22.1 ± 0.6	1.8 ± 0.8	4.38E+14	17.8 ± 0.3	20.8 ± 0.3	3.0 ± 0.4
9-14	20.3 ± 0.6	22.1 ± 0.6	1.8 ± 0.8	1.05E+15	14.2 ± 0.3	20.0 ± 0.3	5.8 ± 0.4
11-13	20.2 ± 0.6	22.0 ± 0.6	1.8 ± 0.8	2.06E+15	-	-	-

Sensor	Unirradiated			Fluence [neq/cm <sup>2</sup> ]	Irradiated		
	V <sub>gl</sub> [V]	V <sub>fd</sub> [V]	V <sub>bulk</sub> [V]		V <sub>gl</sub> [V]	V <sub>fd</sub> [V]	V <sub>bulk</sub> [V]
1	26.1 ± 0.5	27.9 ± 0.5	1.8 ± 0.8	1.79E+14	25.0 ± 0.3	26.8 ± 0.3	1.8 ± 0.4
2	27.3 ± 0.6	29.4 ± 0.6	2.1 ± 0.9	1.79E+14	25.2 ± 0.3	26.6 ± 0.3	1.4 ± 0.4
3	27.3 ± 0.6	29.4 ± 0.6	2.1 ± 0.9	4.38E+14	23.2 ± 0.3	26.6 ± 0.3	3.4 ± 0.4
4	27.9 ± 0.5	29.1 ± 0.5	1.2 ± 0.7	4.38E+14	23.8 ± 0.5	26.6 ± 0.3	2.8 ± 0.7
8	26.1 ± 0.5	27.9 ± 0.5	1.8 ± 0.8	1.05E+15	18.5 ± 0.6	24.6 ± 0.5	6.1 ± 0.8
9	27.9 ± 0.5	29.1 ± 0.5	1.2 ± 0.7	1.05E+15	18.4 ± 0.3	24.4 ± 0.3	6.0 ± 0.4
12	27.3 ± 0.5	29.3 ± 0.6	2.0 ± 0.8	2.06E+15	12.6 ± 0.7	19.8 ± 0.3	7.2 ± 0.8
13	26.7 ± 0.6	28.7 ± 0.6	2.0 ± 0.8	2.06E+15	14.2 ± 0.3	20.3 ± 0.3	6.1 ± 0.4

# Acceptor removal constants can be estimated from gain layer depletion voltages



AC-LGADs wafer 3073 ( $c_\gamma$ )	DC-LGADs wafer 3076 ( $c_{ni}$ )	AC-LGADs wafer 3080 ( $c_{ni}$ )
$(8.59 \pm 0.98) \times 10^{-9} \text{ Gy}^{-1}$	$(3.28 \pm 0.19) \times 10^{-16} \text{ cm}^2/n_{eq}$	$(3.49 \pm 0.15) \times 10^{-16} \text{ cm}^2/n_{eq}$

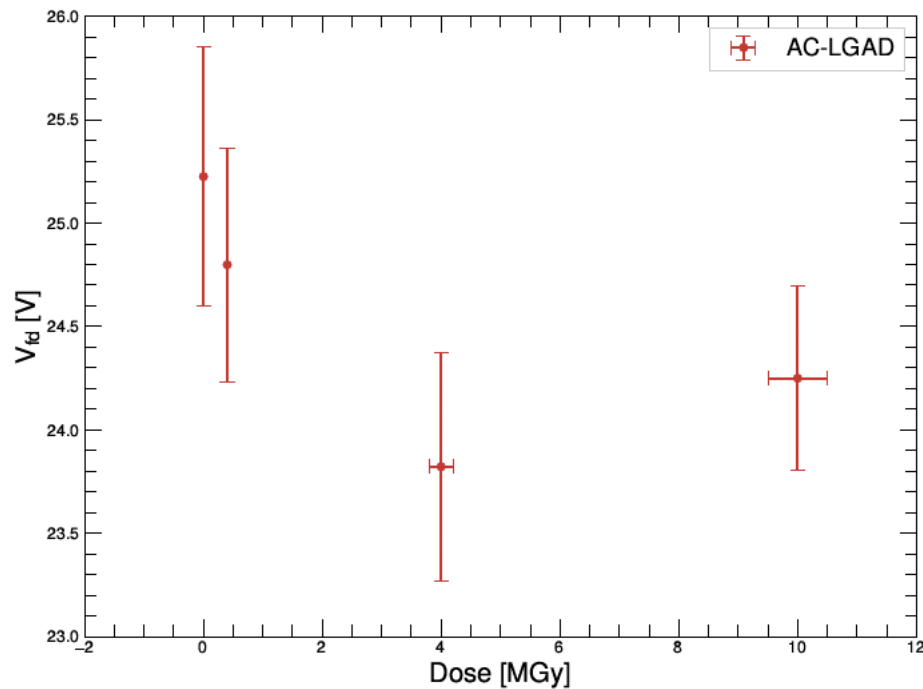
These acceptor removal constants are consistent with those measured for DC-LGADs by a different producer under complementary conditions.<sup>1,2</sup>

<sup>1</sup> M.R. Hoferkamp et al., <https://www.frontiersin.org/articles/10.3389/fphys.2022.838463>.  
<sup>2</sup> J. Sorenson et al., 2024 JINST 19 P05012.

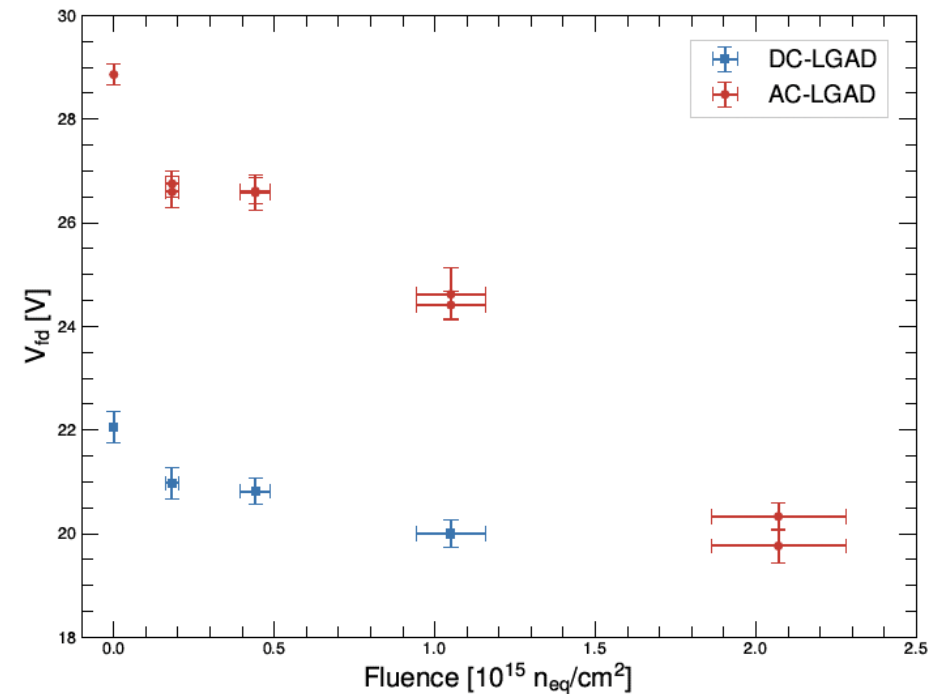


# Full depletion voltage decreases with increasing irradiation exposure.

$V_{fd}$  versus ionizing dose



$V_{fd}$  versus non-ionizing dose



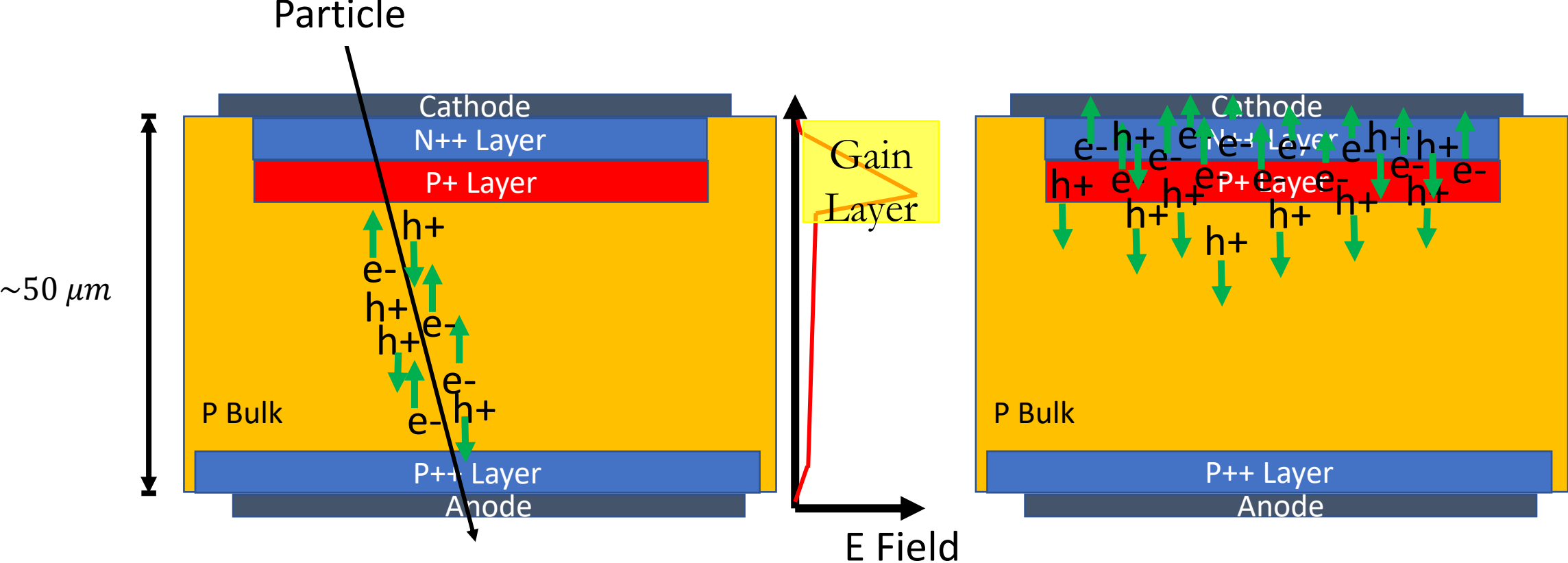
# Summary

- BNL AC/DC-LGADs were irradiated by gammas/protons.
- Gamma irradiation of strip AC-LGADs:
  - Leakage current increases  $\sim 10$ 's of nA and breakdown voltage increases  $< 10\%$ ;
  - Inter-pad resistance decreased up to  $10^6$  times after gamma-irradiation;
  - Measured capacitance is affected by the low inter-pad resistance and shows frequency dependence;
  - Gain layer depletion voltage decreases up to  $\sim 2$ V.
- Proton irradiation of DC-LGADs and Pixel AC-LGADs:
  - Leakage current increases  $\sim 10$ 's of  $\mu$ A and breakdown voltage up to  $\sim 100$ 's of volts;
  - Gain layer depletion voltage decreases up to  $\sim 10$ 's of volts.
- Acceptor removal constants are consistent with measurements in complementary conditions.
  - $c_\gamma = 8.6 \times 10^{-9} \text{ Gy}^{-1}$
  - $c_{ni} = (3.3 - 3.5) \times 10^{-16} \text{ cm}^2/n_{\text{eq}}$

Thank You!

# Backup Slides

# How LGAD works

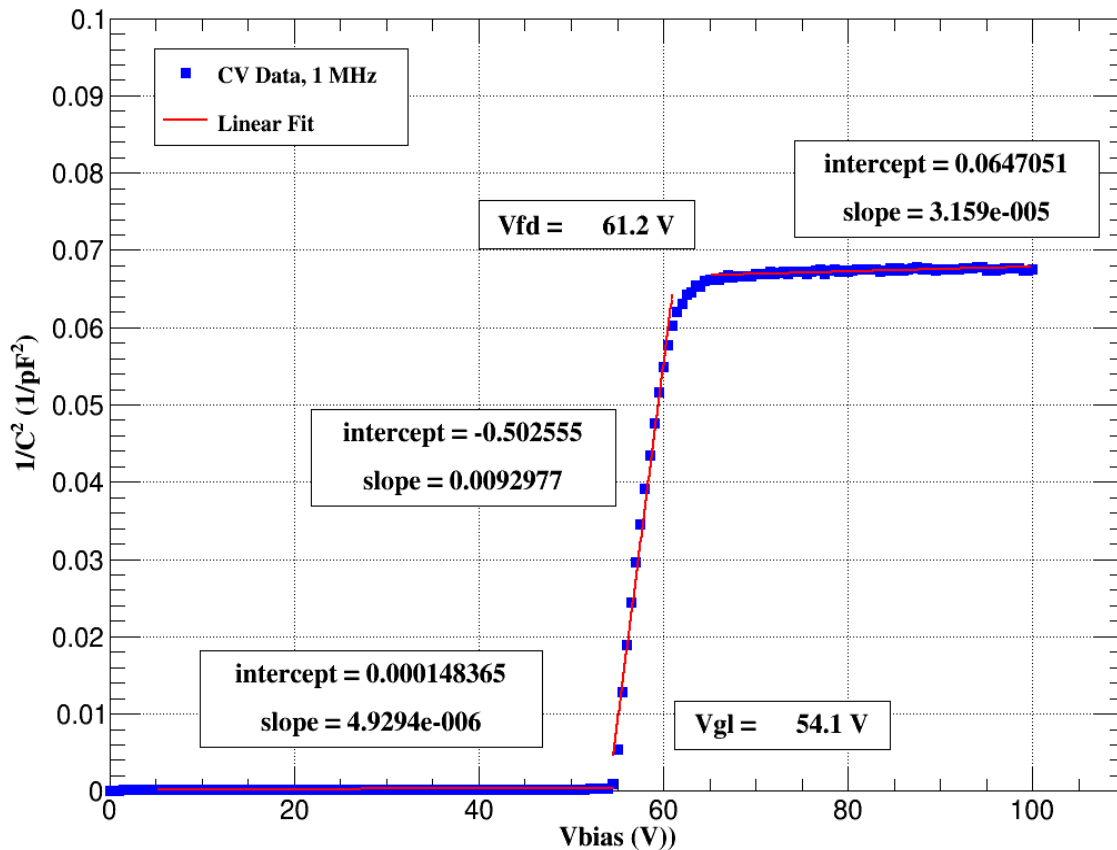


In silicon sensors, charge multiplication happens when charge carriers drift in a region with an electric field (E) greater than about 300 kV/cm. The additional P+ (or gain) layer, when depleted, locally generates an electric field high enough to activate the avalanche process.



# CV Measurements are used to extract the gain layer depletion voltage $V_{gl}$ and full depletion voltage $V_{fd}$

W25 Pre-Irradiated 1E14 A



The depletion voltage of the gain layer depends on the dopant concentration, which is impacted by radiation fluence

Dopant Concentration

Electron charge

Gain Layer depth

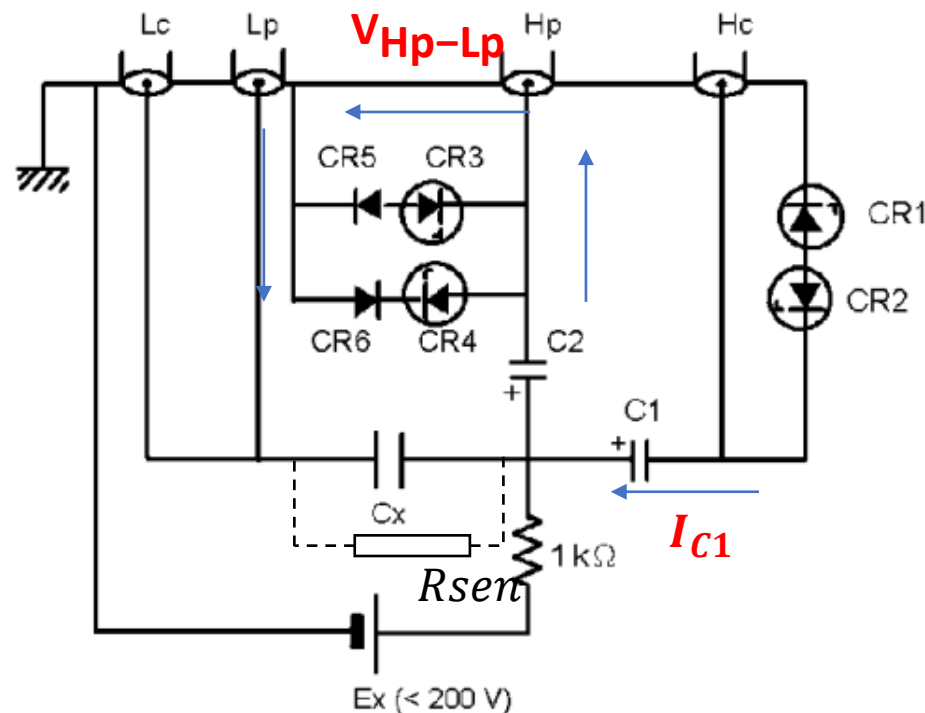
Gain layer depletion voltage

$$V_{gl} = \frac{qN_A w^2}{2\epsilon} \left(1 + 2\frac{d}{w}\right)$$

Permittivity of Silicon

Gain Layer Thickness

Manufacturer recommended bias isolation box was used for the CV measurements. Gamma-irradiation can cause surface damage and lower the equivalent parallel resistance of the detector. A study of how the values of the parts in the circuit can affect the measurement is needed.



$$C_{measured} = Re\left[\frac{1}{j\omega}(I_{C1}/V_{Hp-Lp})\right]$$

where Cx: Sample capacitor  
 Ex: External DC bias voltage source  
 C1: Blocking capacitor

$$\text{Capacitance value} \geq \frac{1}{10\pi f}$$

(f: measurement frequency (Hz))

DC withstand voltage: > Ex

C2: Blocking capacitor

Capacitance value: 1 μF

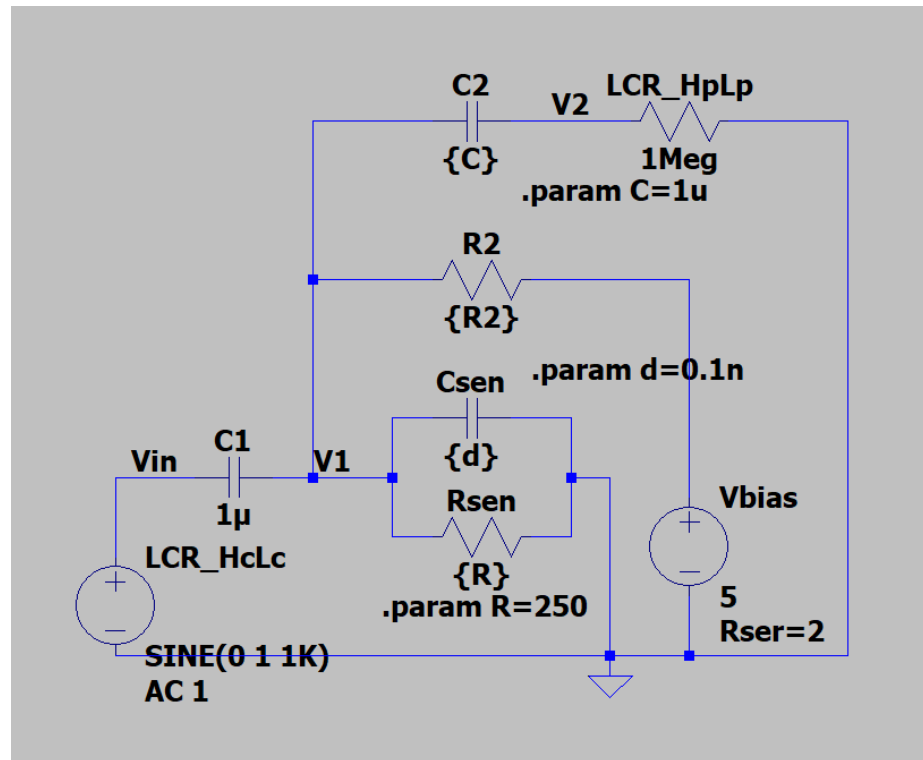
DC withstand voltage: Ex

CR1, CR2: Diode-zener, 47 V, 5% 1 W

CR3, CR4: Diode-zener, 3.3 V, 5% 1 W

CR5, CR6: Diode-power, 200 V, 1 A

# Smaller equivalent parallel resistance of the DUT can cause bigger discrepancy between the measured value and real value of the DUT capacitance



$$C_{measured} = C_{sen} - \left( \frac{1}{R_{sen}} + \frac{1}{R2} \right) \frac{1}{C_2 R_{HpLp} \omega^2}$$

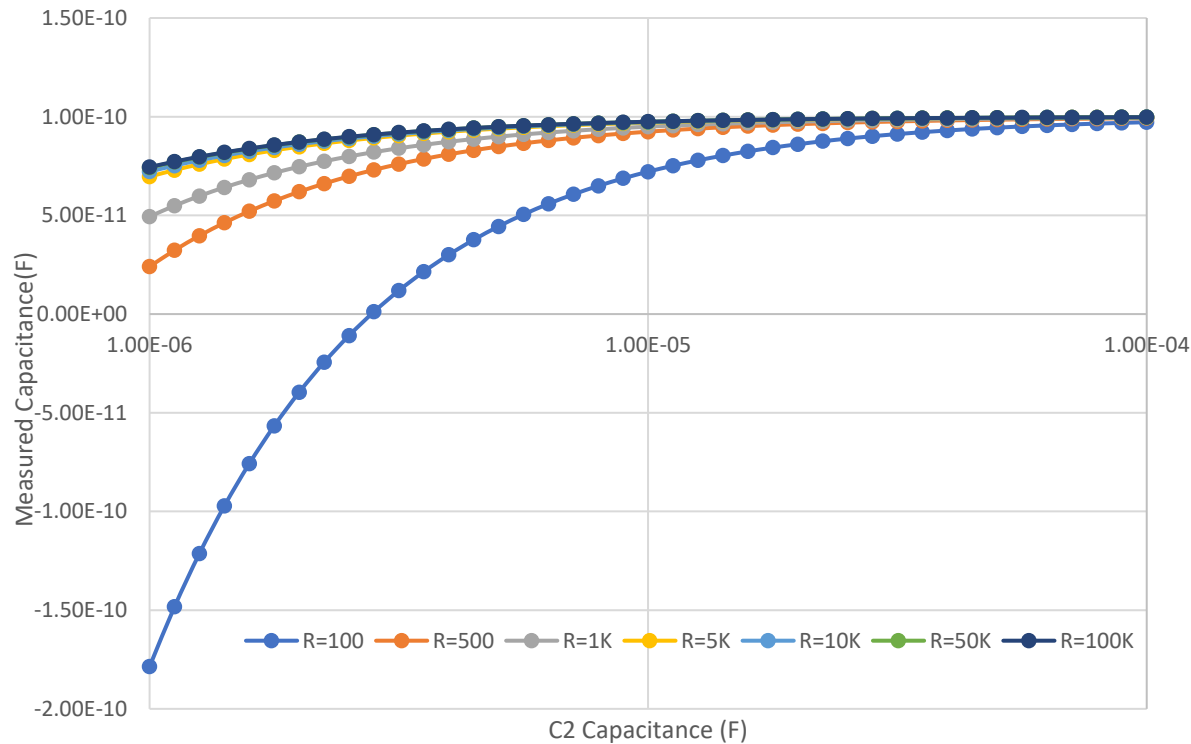
$$R_{sen} = R_{bulk}(\omega, V_{bias}) \parallel \left[ R_{intpad}(\omega, V_{bias}) + R_{GR}(\omega, V_{bias}) \right]$$

Bigger  $C_2$ ,  $\omega$  can make error smaller. However, too small  $R_{sen}$  requires an impractically big  $C_2$ .

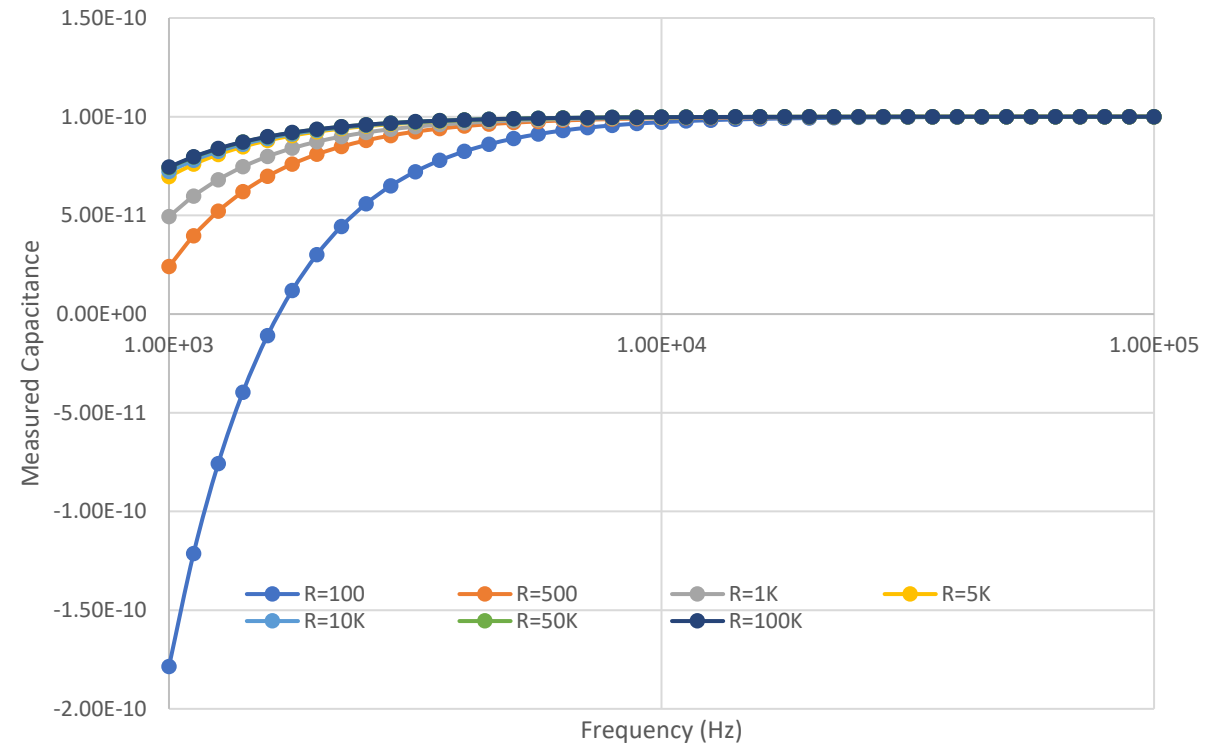
Bigger  $R2$  can reduce error. However,  $R2$  can't not be too big because it would take too much time to make  $V_{bias}$  stable.

# Simulation with LTSpice shows that the error decreases as C2 increases, while as frequency and parallel resistance increase.

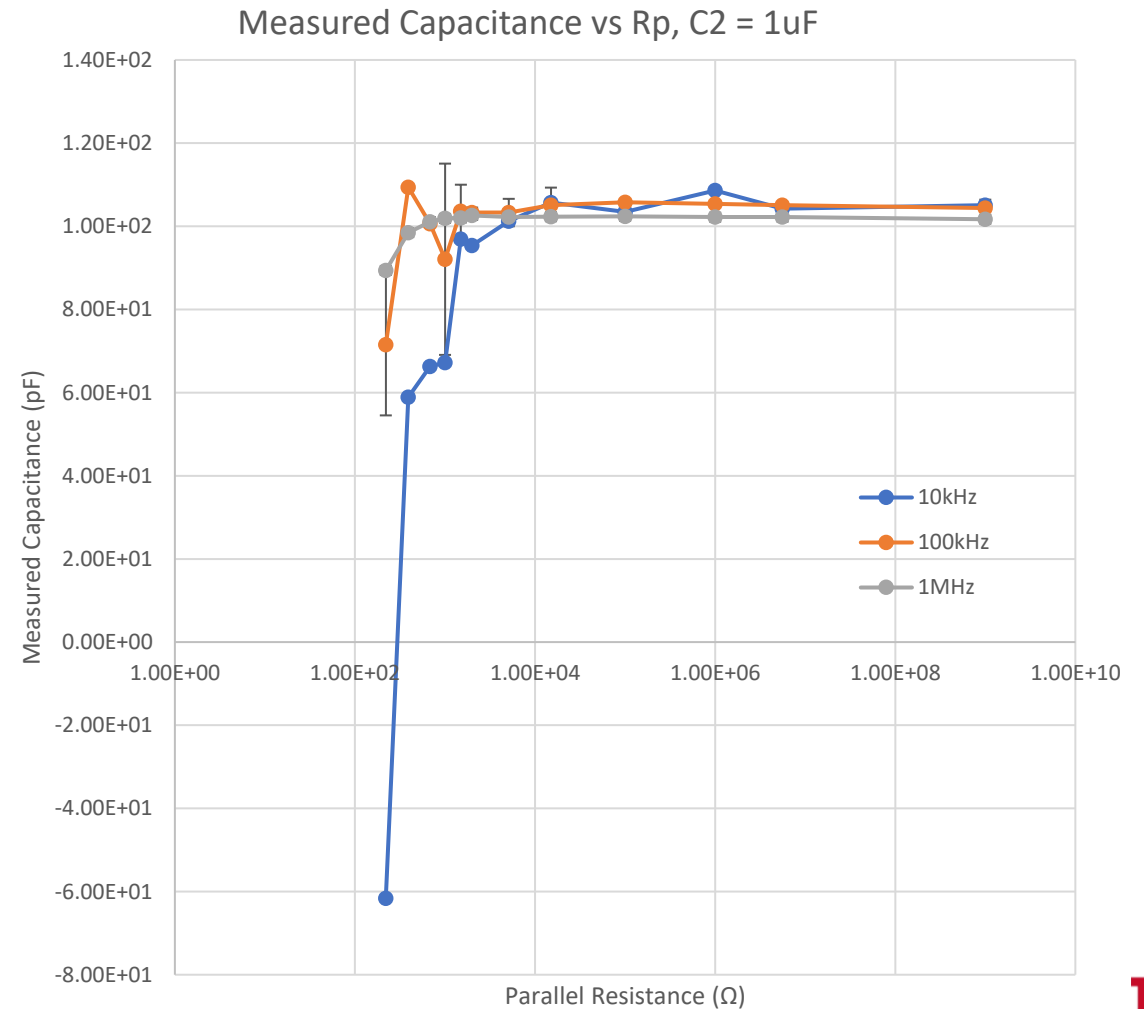
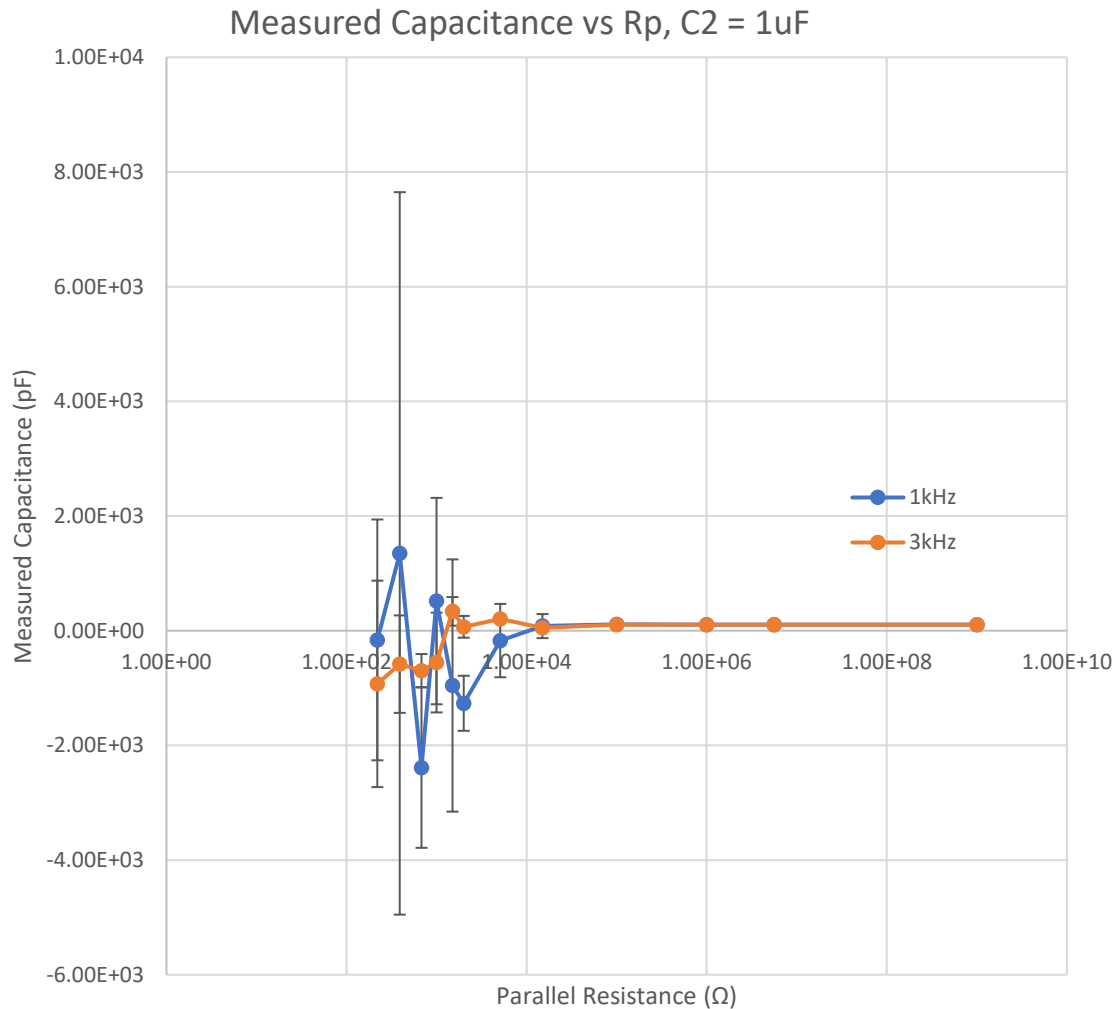
Measured Capacitance vs C2 values (f=1kHz)



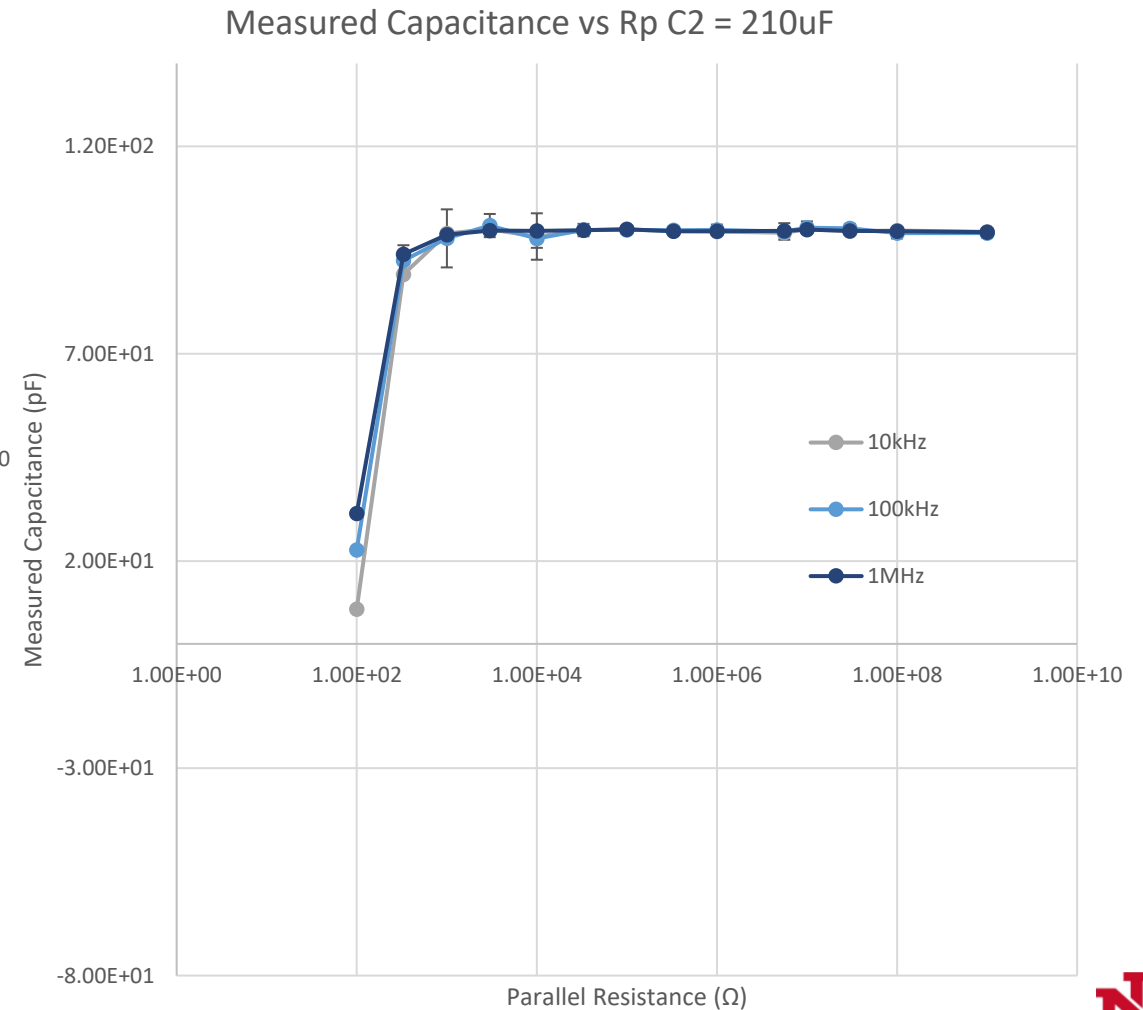
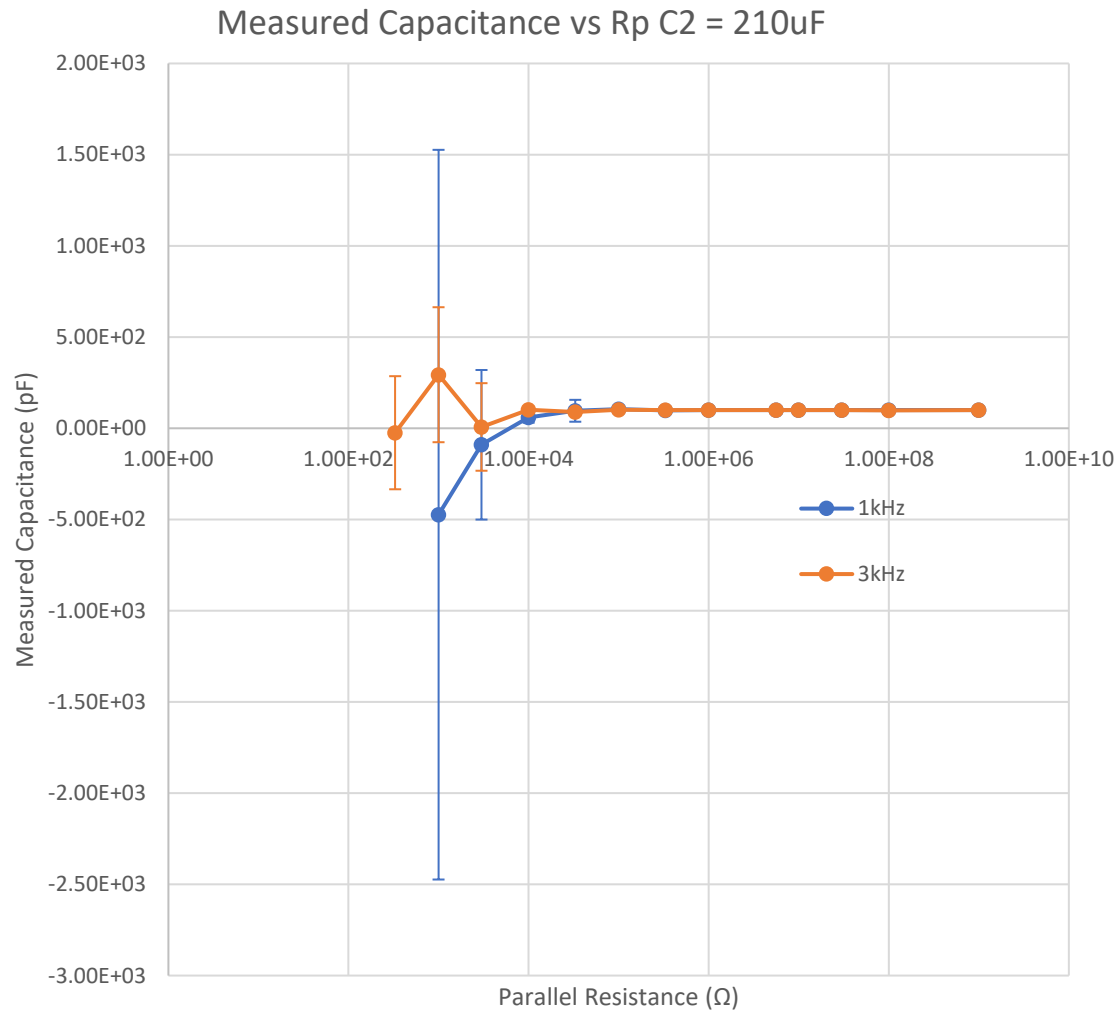
Measured Capacitance vs Frequency (C2 = 1uF)



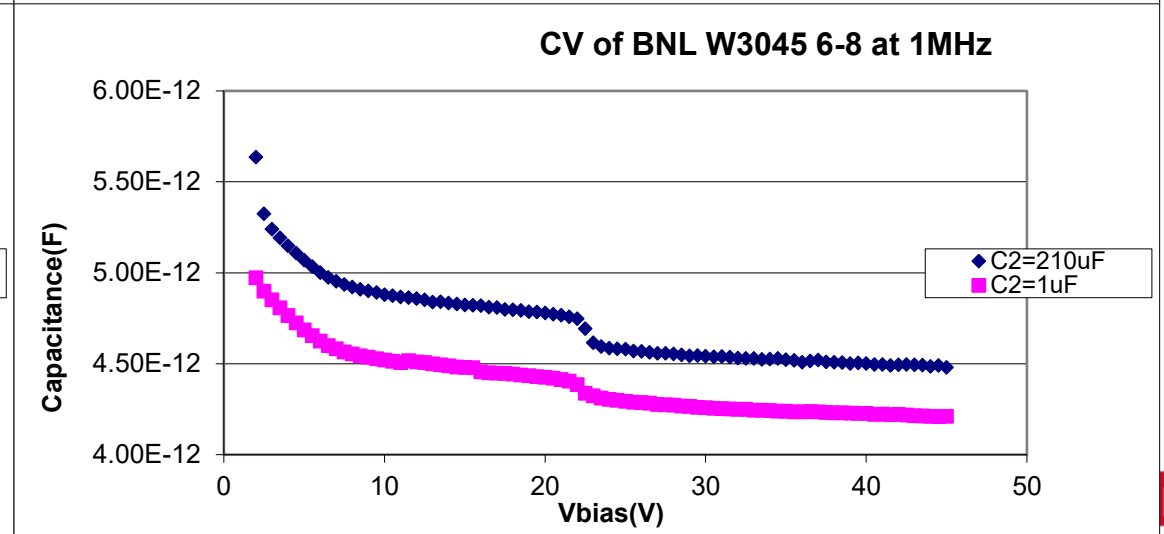
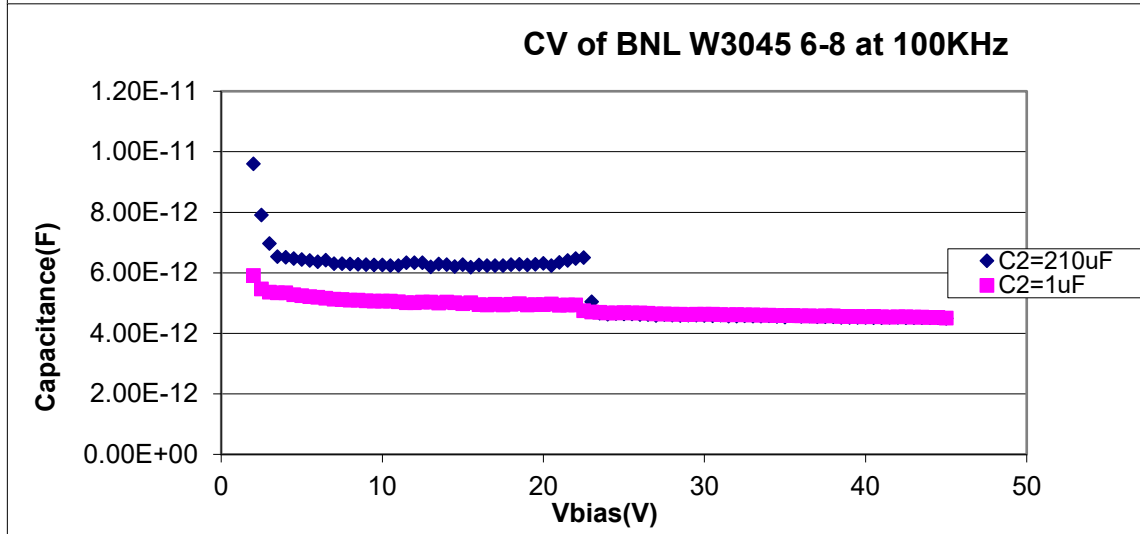
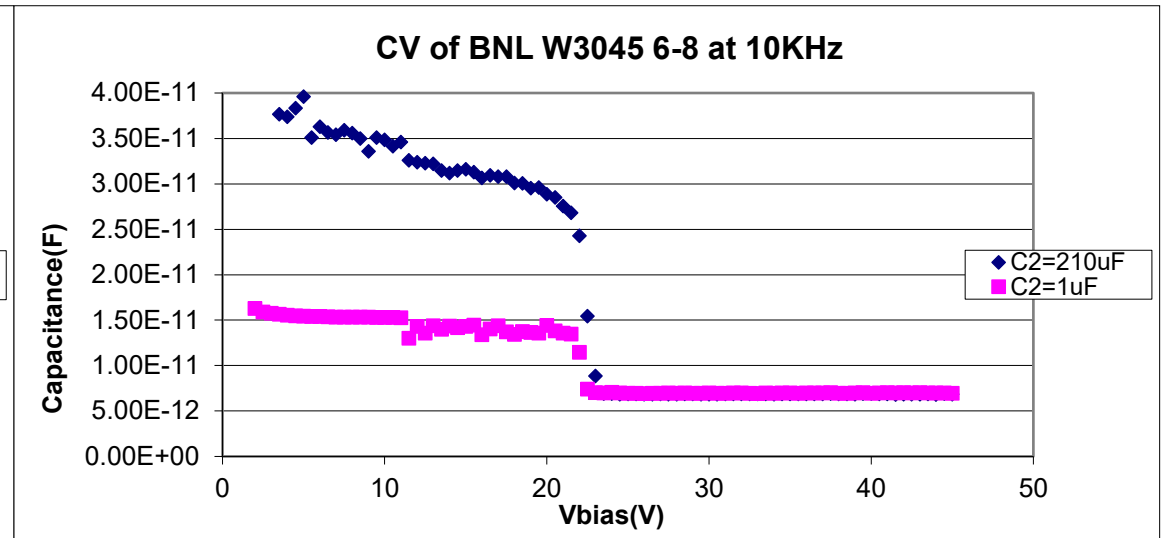
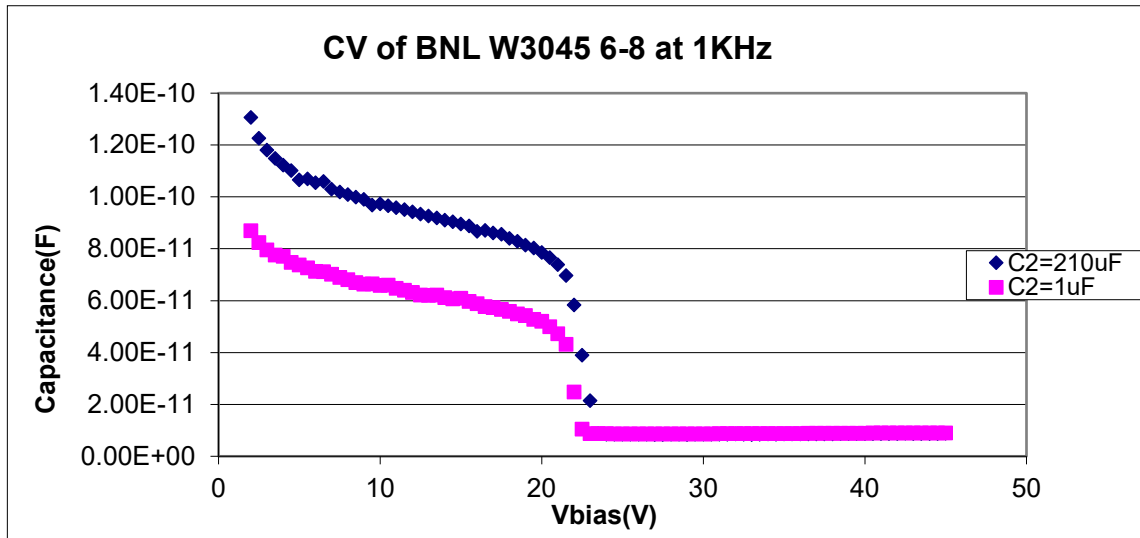
# Test Measurement with a 100pF ceramic capacitor and different parallel resistors shows that lower $R_p$ can cause bigger errors.



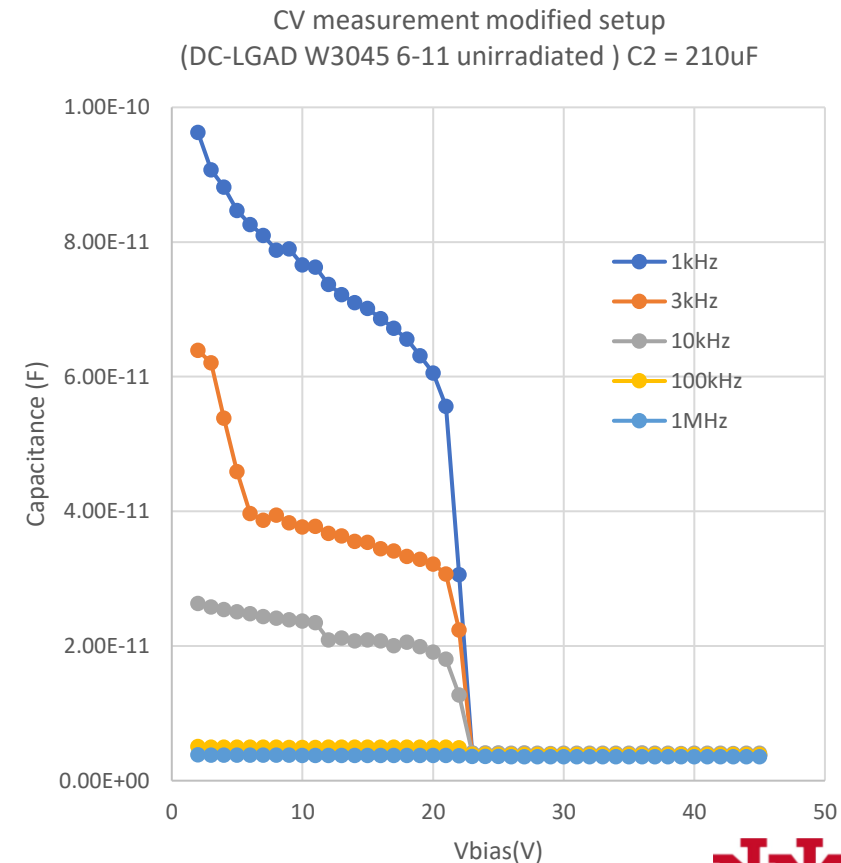
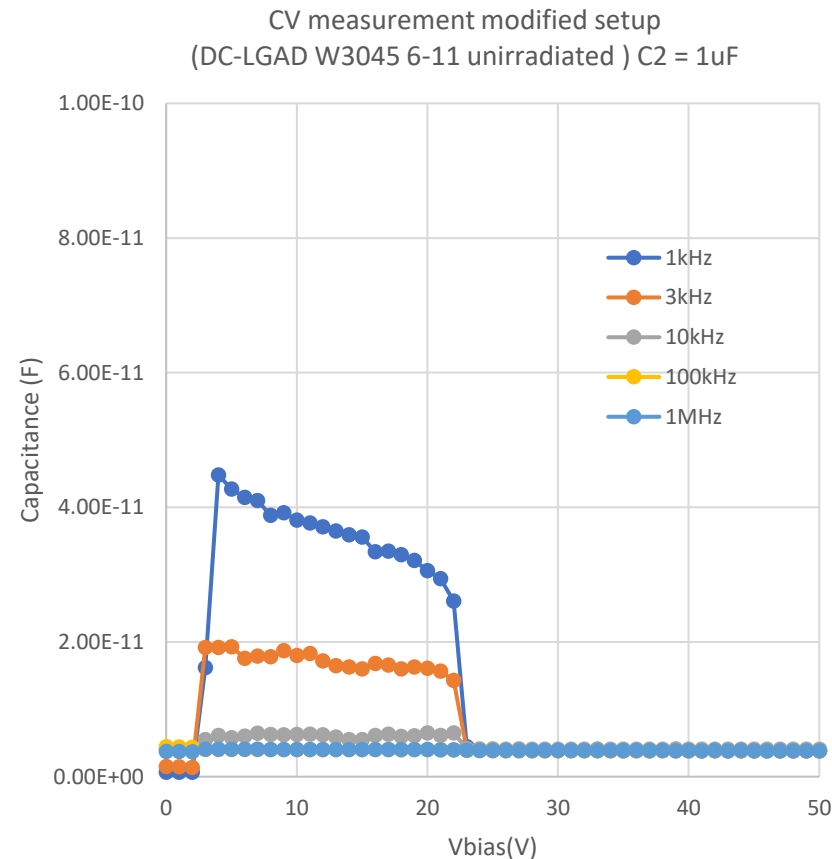
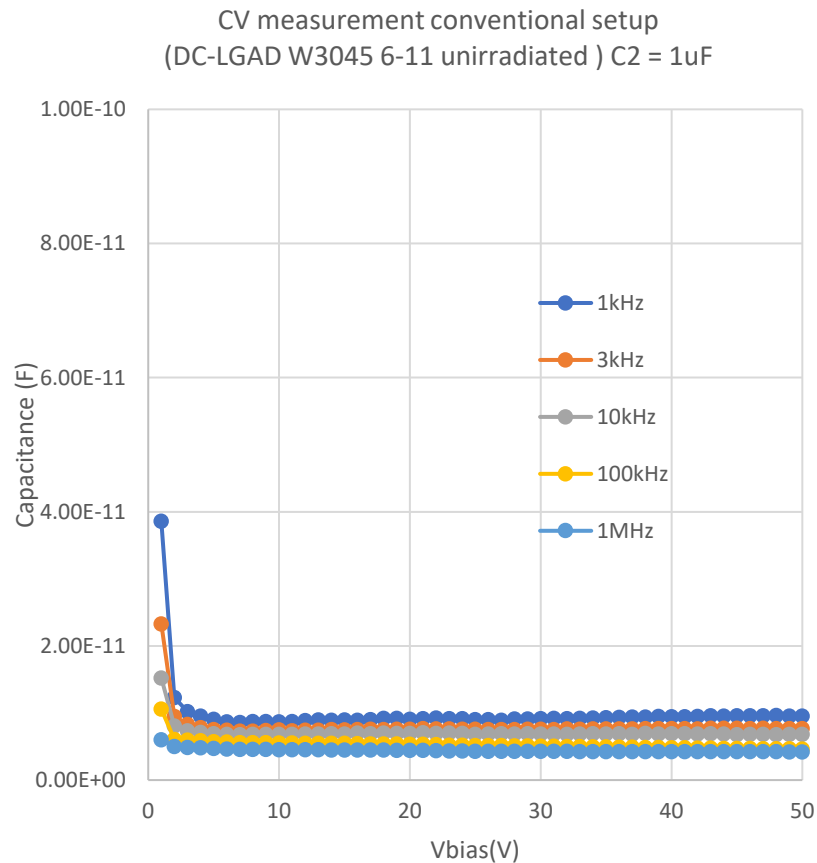
# Test Measurement with a 100pF ceramic capacitor shows a bigger C2 (=210uF) can improve the capacitor measurement.



Bigger  $C_2$  can make error smaller. However, measured capacitance also decreases as test frequency increases.



# With the new setup and a big C2, the feature is much clearer than the conventional setup.

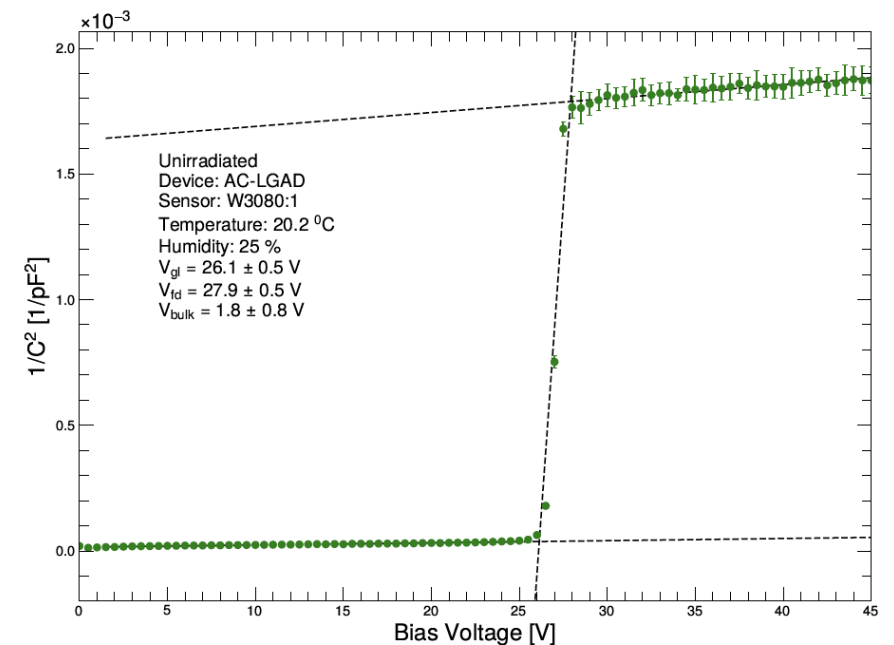
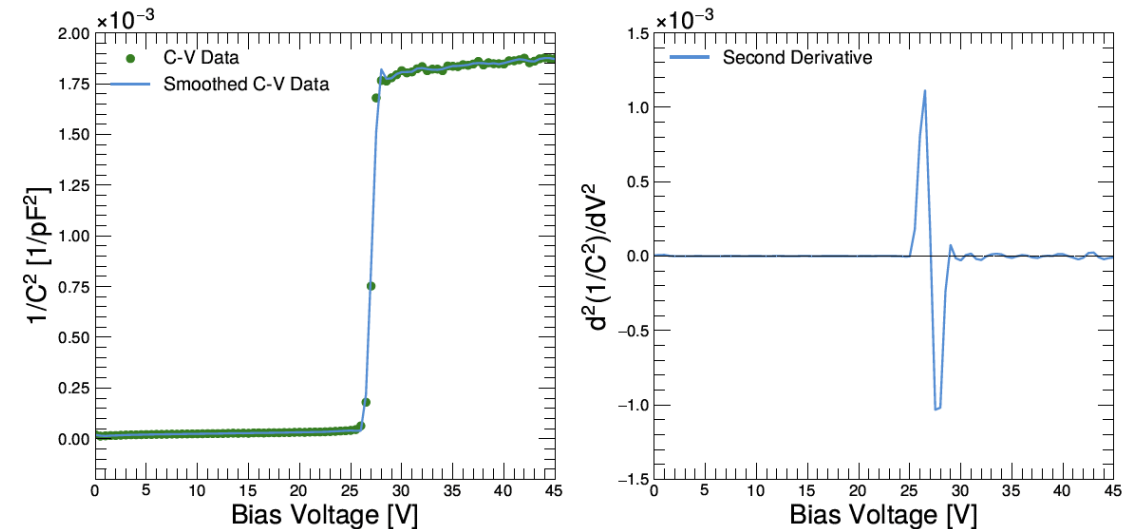


# Extraction of $V_{gl}$ and $V_{fd}$

(upper left): Raw capacitance data vs. applied bias. Smoothed function obtained with Savitzky-Golay filter.\*

(upper right): Second derivative of the smoothed function. Spikes define limits  $V_1$  and  $V_2$  of the data to which 3 fitted lines are applied.

(bottom): Data selected from the smoothed function are used to fit three lines in regions separated by  $V_1$  and  $V_2$ . Lower and upper crossing points define  $V_{gl}$  and  $V_{fd}$ .



\*Anal. Chem. 36, no. 8, 1627-1639 (2002).